Drilling flexible forms, blind and hole drilling, cutting, in- and on-glass markings, structuring, removal of coatings - the all-in-one solution from MDI Advanced Processing GmbH

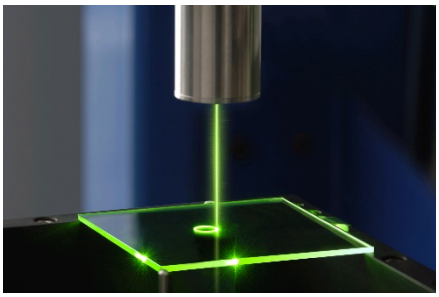
LD 500: Glass processing for small substrates



The glass processing systems of the LD series from MDI Advanced Processing GmbH offer high-quality processing of brittle materials for a variety of industrial applications due to the laser technology used (532nm).

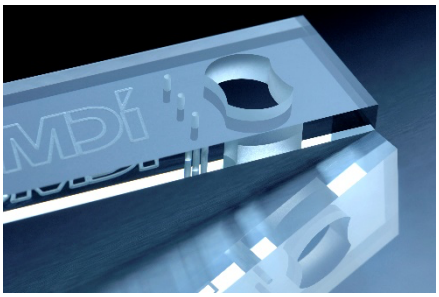
Technology and process

The "Green Laser" enables drilling of flexible shapes, blind and hole drilling, cutting, marking in and on the glass, structuring and removal of coatings in one system. The process is based on a solid-state laser that emits green light with a wavelength of 532 nm, maximum precision for your application.



Technical Data

- substrate size: max. 500 x 500 mm
- glass thickness: 0.3 – 200 mm
- position/ repeatability: ± 0.1 mm / ± 0.05 mm
- dimension (L x B x H): min. 1.800 x 1.400 x 2.100 mm



Options

- customization
- various table and clamping designs
- software tools (DXF-converter)

MDI Advanced Processing GmbH would be happy to provide you with detailed information about the LD series and show you the advantages for your company.

Please contact us if you have any questions or are interested in a live demonstration of our technologies and products.

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MDI Advanced Processing GmbH

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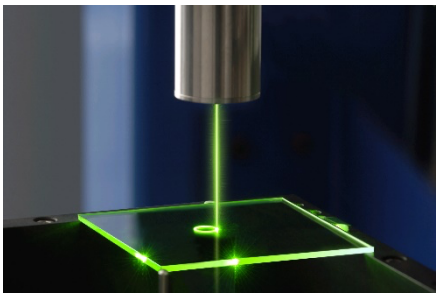
LD 650: Glass processing for medium substrates

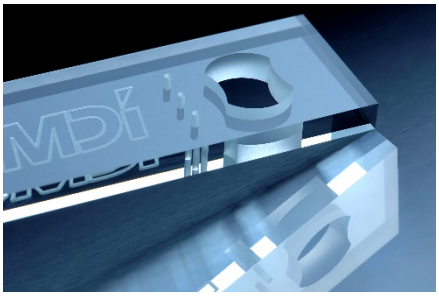


The glass processing systems of the LD series from MDI Advanced Processing GmbH offer high-quality processing of brittle materials for a variety of industrial applications due to the laser technology used (532nm).

Technology and process

The "Green Laser" enables drilling of flexible shapes, blind and hole drilling, cutting, marking in and on the glass, structuring and removal of coatings in one system. The process is based on a solid-state laser that emits green light with a wavelength of 532 nm, maximum precision for your application.





Technical data

- substrate size: max. 950 x 650 mm
- glass thickness: 0.3 – 200 mm
- position/repeatability : ± 0.05 mm / ± 0.25 mm
- dimensions (L x B x H): min. 2.800 x 1.900 x 2.100 mm

Options

- customization
- various table and clamping designs
- software tools (DXF-converter)
- alignment System
- laser power measurement
- automization

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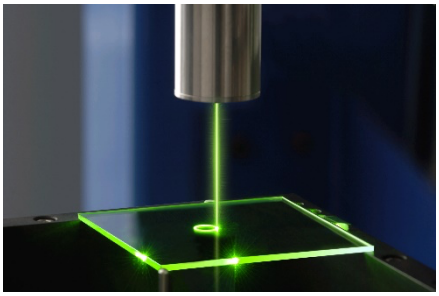
LD 2000: Glasprocessing for large substrates

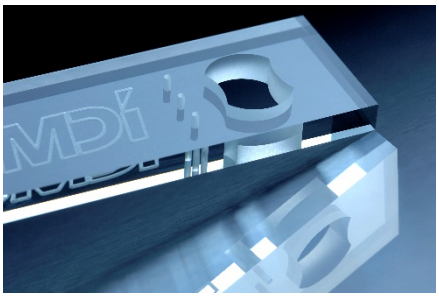


The glass processing systems of the LD series from MDI Advanced Processing GmbH offer high-quality processing of brittle materials for a variety of industrial applications due to the laser technology used (532nm).

Technology and process

The "Green Laser" enables drilling of flexible shapes, blind and hole drilling, cutting, marking in and on the glass, structuring and removal of coatings in one system. The process is based on a solid-state laser that emits green light with a wavelength of 532 nm, maximum precision for your application.





Technical data

- substrate size: max. 2000 x 1500 mm
- glass thickness: 0.3 – 200 mm
- position/repeatability: ± 0.1 mm / ± 0.05 mm
- dimensions (L x B x H): min. 3.500 x 3.300 x 2.100 mm

Options

- customization
- various table and clamping designs
- software tools (DXF-converter)
- alignment System
- laser power measurement
- automization

MDI Advanced Processing GmbH would be happy to provide you with detailed information about the LD series and show you the advantages for your company.

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